

What I claim is:

1. An arrangement including:

- an electrical subassembly,
- an optical subassembly,

5       - said electrical subassembly and said optical subassembly having an associated electrical connection including at least one electrical lead extending therebetween, and

10       - at least electrically non-conductive absorber body arranged to at least partly cover said at least one electrical lead.

2. The arrangement of claim 1, wherein said electrical connection includes a lead frame comprising a plurality of said electrical leads, said absorber  
15 body arranged to extend over said lead frame.

3. The arrangement of claim 1, further including a dielectric support board, wherein said electrical connection extends over said support board and said at least one electrical lead is arranged between said  
20 absorber body and said support board.

4. The arrangement of claim 3, including at least one further electrically non-conductive electromagnetic absorber body associated with said supporting board, wherein said at least one electrical lead is sandwiched  
25 between said at least one absorber body and said at least one further absorber body.

5. The arrangement of claim 1, wherein said electrical connection is a radio frequency electrical connection between said electrical subassembly and said  
30 optical subassembly.

6. The arrangement of claim 1, including a further optical subassembly and a further electrical connection between said electrical subassembly and said further optical subassembly, said further electrical connection  
35 including at least one further electrical lead, the

arrangement including at least one further electrically non-conductive electromagnetic absorber body arranged to at least partly cover said at least one further electrical lead.

5           7. The arrangement of claim 1, wherein said absorber body is selected out of the group consisting of magnetically loaded, iron loaded, ferrite loaded or dielectrically loaded materials.

10           8. The arrangement of claim 1, wherein said absorber body is comprised of a material selected from the group consisting of silicon, urethane, vinyl plastic and silicon rubber.

          9. The arrangement of claim 1, wherein said absorber body is in the form of a sheet material.

15           10. An arrangement including:

- a support board of a dielectric material,
- at least one electrically conductive lead for conveying RF signals over said support board, and
- at least one electrically non-conductive

20 electromagnetic absorber body arranged to at least partly cover said at least one electrical lead.

          11. The arrangement of claim 10, including a plurality of said electrical leads in a frame, said at least one absorber body arranged to extend over said

25 lead frame.

          12. The arrangement of claim 10, wherein said at least one electrical lead is arranged between said absorber body and said support board.

30           13. The arrangement of claim 12, including at least one further electrically non-conductive electromagnetic absorber body associated with said support board, wherein said at least one electrical lead is sandwiched between said at least one absorber body and said at least one further absorber body.

14. The arrangement of claim 10, wherein said electrical lead is a radio frequency electrical connection.

15. The arrangement of claim 10, wherein said absorber body is selected out of the group consisting of magnetically loaded, iron loaded, ferrite loaded or dielectrically loaded materials.

16. The arrangement of claim 10, wherein said absorber body is comprised of a material selected from the group consisting of silicon, urethane, vinyl plastic and silicon rubber.

17. The arrangement of claim 10, wherein said absorber body is in the form of a sheet material.

18. An arrangement including:

- a support board of a dielectric material,
- at least one electrically conductive lead for conveying RF signals over said support board, and
- at least one electrically non-conductive electromagnetic absorber body arranged to at least partly cover said at least one electrical lead.

19. A casing for communication apparatus, said apparatus including at least one electrical lead for carrying RF signals within the apparatus, the casing including at least one electrically non-conductive electromagnetic absorber body arranged to at least partly cover said electrical lead.

20. The casing of claim 19, having associated a dielectric support board for said at least one electrical lead, wherein said at least one lead is adapted to arranged between said absorber body and said support board.

21. The casing of claim 19, wherein said absorber body is selected out of the group consisting of magnetically loaded, iron loaded, ferrite loaded or dielectrically loaded materials.

22. The casing of claim 19, wherein said absorber body is comprised of a material selected from the group consisting of silicon, urethane, vinyl plastic and silicon rubber.

5        23. The casing of claim 19, wherein said absorber body is in the form of a sheet material.

24. An arrangement including:

- a supporting board of dielectric material,
- at least one electrically conductive lead for
- 10 conveying RF signals over said board, and
- at least one electrically non-conductive electromagnetic absorber body arranged to at least partly cover said at least one electrical lead.